PRODUCT/PROCESS CHANGE NOTIFICATION

PCN IPD-IPC/13/8067
Dated 27 Sep 2013

SRK2000D : Metal mask change

Table 1. Change Implementation Schedule

Forecasted implementation date for change	20-Sep-2013
Forecasted availability date of samples for customer	20-Sep-2013
Forecasted date for **STMicroelectronics** change Qualification Plan results availability	20-Sep-2013
Estimated date of changed product first shipment	27-Dec-2013

Table 2. Change Identification

Product Identification (Product Family/Commercial Product)	SRK2000D and SRK2000DTR
Type of change	Product design change
Reason for change	To improve product performance in high power applications.
Description of the change	The change consists in removing a connection between the internal temperature sensor and the driver section.
Change Product Identification	By a new internal part number
Manufacturing Location(s)	

DOCUMENT APPROVAL

Name	Function
Gherdovich, Gabriele	Marketing Manager
Sandrini, Francesca Marta	Product Manager
Motta, Antonino	Q.A. Manager

ATTACHMENT TO PCN IPG-IPC/13/8067

WHAT*:*

We have removed a residual connection from the internal temperature sensor to the driver section, not reported in the spec. but shown in the internal block diagram, as per the updated internal block diagram (fig.1)

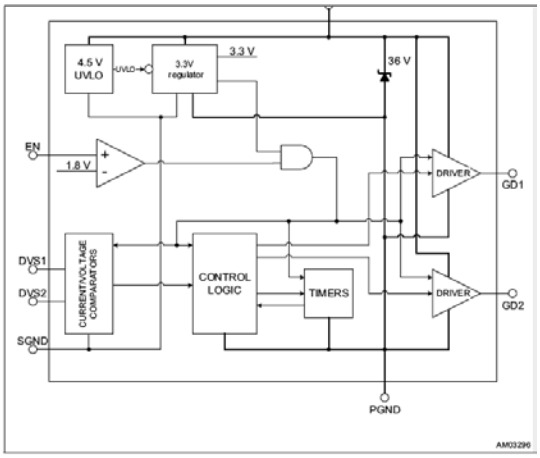

Figure 1 Updated internal block diagram

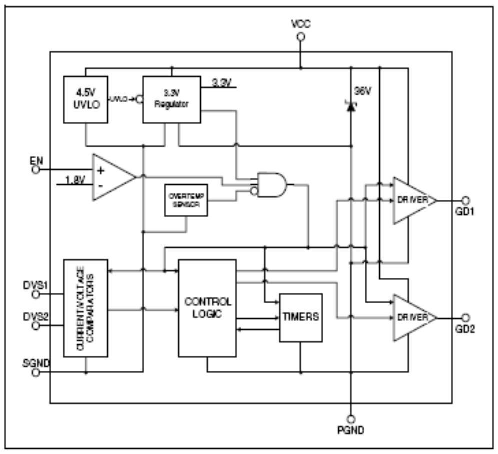

Figure 2 Old internal block diagram

WHY*:*

In order to improve the product performance in applications requiring high temperature and high power.

HOW*:*

Through a metal mask change, which will be identified by a new internal part number, as follows :

Commercial Product	Packing type	Old internal part number	New internal part number
SRK2000D	Tube	SRK2000D-4LF/	SRK2000D-9LF/
SRK2000DTR	Tape&Reel	SRK2000DTR-4LF/	SRK2000DTR-9LF/

The functionalities and parameters of the product will remain unchanged.

WHEN*:*

We will implement the change in September, 2013 and can start shipping the new product within Q4, 2013.

Samples are available and can be delivered upon request.

Product Reliability Certificate

Line :……………………….…...… UQ27 AG5
Division :……………………..….IND.& POWER CONV.
Function :………………………SR Smart Driver for LLC resonant converter
Aim of the Qualification:……… New version

Device construction note

DIE FEATURES		
Wafer Code	**:**	UQ27 AG5
Diffusion Site	**:**	CATANIA
Wafer Diameter (inches)	**:**	8 inches
Die Size X	**:**	1081 µm
Die Size Y	**:**	1196 µm
Process Technology	**:**	BCD6S
Passivation	**:**	USG+SiN+Polymide

PACKAGE FEATURES		
Package Code Description	**:**	SO8
Assembly Site	**:**	AMKOR ATP1-PHILIPPINES
Die Attach material	**:**	Ablebond 8290
Bonding wire 1 material	**:**	Au
Bonding wire 1 diameter (mils)	**:**	1 mils
Molding compound	**:**	Sumitomo G600
Lead / Ball / Bump solder	**:**	Sn

Ojectives:

The UQ27 AG5 device is a metal option of the already qualified UQ27 AD5 device (see RR002909CS2047). Considering that this metal change is marginal from reliability viewpoint, the positive results of the reliability trial performed on previous revision can be extended to UQ27 AG5 per similarity.

Conclusion:

This certificate assures that the device UQ27 AG5 with the above construction notes passed the reliability evaluation and can be put in mass production from reliability point of view.

Approved by:

Author: ***Gianfranco D'Angelo***
Approval: ***Alceo Paratore***

Public Products List

PCN Title : SRK2000D : Metal mask change
PCN Reference : IPD-IPC/13/8067
PCN Created on : 30-SEP-2013

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change:

ST COMMERCIAL PRODUCT

SRK2000D	SRK2000DTR

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